

Data sheet acquired from Harris Semiconductor SCHS060C - Revised September 2003

CMOS Dual 2-Wide 2-Input AND-OR-INVERT Gate

High-Voltage Types (20-Volt Rating)

■ CD4085 contains a pair of AND-OR-INVERT gates, each consisting of two 2-input AND gates driving a 3-input NOR gate. Individual inhibit controls are provided for both A-O-I gates.

The CD4085B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

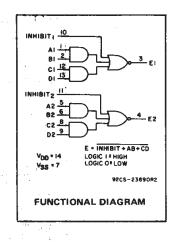
MAXIMUM RATINGS, Absolute-Maximum Values:

Features:

- Medium-speed operation tpHL = 90 ns; tp_H = 125 ns (typ.) at 10 V
- Individual inhibit controls
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 µA at 18 V over full packagetemperature range; 100 nA at 18 V and 25°C
- Noise margin (over full packagetemperature range):

1 V at V_{DD} = 5 V 2 V at V_{DD} = 10 V 2.5 V at V_{DD} = 15 V ■ 5-V, 10-V, and 15-V parametric ratings

- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



CD4085B Types

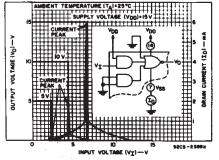


Fig. 1 — Typical voltage and current transfer characteristics.

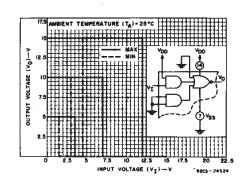


Fig. 2 — Min. and max. voltage transfer characteristics.

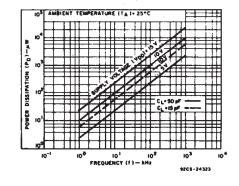


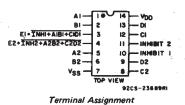
Fig. 3 — Typical power dissipation vs. frequency.

DC SUPPLY-VOLTAGE RANGE, (VDD) Voltages referenced to VSS Terminal)-0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} +0.5V DC INPUT CURRENT, ANY ONE INPUT±10mA POWER DISSIPATION PER PACKAGE (PD): DEVICE DISSIPATION PER OUTPUT TRANSISTOR OPERATING-TEMPERATURE RANGE (TA).....-55°C to +125°C STORAGE TEMPERATURE RANGE (T_{81g}).....-65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING):

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIA	UNITS	
	Min.	Max.	
Supply-Voltage Range (For TA=Full Package-			. v
Temperature Range)	3	18	



CD4085B Types

STATIC ELECTRICAL CHARACTERISTICS

							*			10 3	
CHARAC-	CONDITIONS			LIMI	TS AT I	NDICAT	ED TEI	MPERA'	UNITS		
TERISTIC	vo	VIN	V_{DD}						+25	11	
	(V)	(V)	(V)	–55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent		0,5	5	1	1	30	30	1	0.02	1	
Device		0,10	10	2	2	60	60		0.02	2	μΑ
Current	_	0,15	15	4	4	120	120		0.02	4	μ
IDD Max.		0,20	20	20	20	600	600	-	0.04	20	
Output Low					7 E	* · ·				7	
(Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1		
Current,	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_	mΑ
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		
(Source)	2.5	0,5	5	_2	-1.8	-1.3	-1.15	-1.6	-3.2		
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	_	
I _{OH} Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	_	
Output Volt-											
age:	_	0,5	5		0.0				0	0.05	
Low-Level,		0,10	10		0.0				0	0.05	
VOL Max.	_	0,15	15		0.0	05		_	0	0.05	v
Output Volt-											,
age:	-	0,5	5		4.9	95		4.95	5	-	
High Level,	_	0,10	10		9.9	95		9.95	10	_	
VOH Min.	_	0,15	15		14.	95		14.95	15	-	
Input Low	0.5,4.5	_	5.		1.	5		_	_	1.5	
Voltage,	1,9		10		3	3		_	-	3	
VIL Max.	1.5,13.5	-	15	4				_	_	4	v
Input High	0.5,4.5	_	5	3.5				3.5	_		v
Voltage,	1,9	_	10	7				7	-		
V _{IH} Min.	1.5,13.5	-	15	11				11	_	_	
Input									-		
Current,	-	0,18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μΑ
I _{IN} Max.											

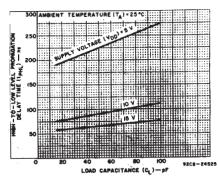


Fig. 4 - Typical data high-to-low level propagation delay time vs. load capacitance.

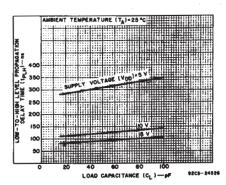


Fig. 5 — Typical data low-to-high level propagation delay time vs. load capacitance.

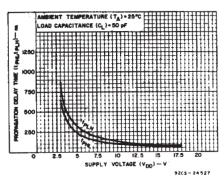


Fig. 6 — Typical data propagation delay time vs. supply voltage.

CD4085B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ = 25°C; Input $t_{\rm f}$, $t_{\rm f}$ = 20 ns, C $_L$ = 50 pF, R $_L$ = 200 K Ω

		CONDITIONS	LIM			
CHARACTERISTIC		V _{DD}	Тур.	Max.	UNITS	
Proposition Dalay Time (Data)		5	225	450		
Propagation Delay Time (Data): High-to-Low Level,	t _{PHL}	10	90	180	ns	
Trigit to East East,	PHL	15	65	130	1	
Low-to-High Level,		5	310	620	ns	
	^t PLH	10	125	250		
		15	90	180		
Propagation Delay Time (Inhibit High-to-Low Level,		5	150	300		
	tPHL	10	60	120	ns	
7.1g. 10 2511 2010.,		15	40	80	1	
		5	250	500	ns	
Low-to-High Level,	^t PLH	10	100	200		
		15	70	140]	
		5	100	200		
Transition Time,	tTHL, tTLH	10	50	100	ns	
		15	40	80	1	
Input Capacitance,	CIN	Any Input	5	7.5	pF	

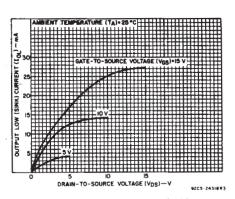


Fig. 7 — Typical output low (sink) current characteristics.

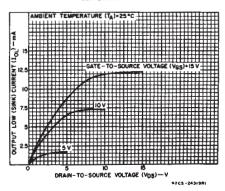


Fig. 8 – Minimum output low (sink) current characteristics.

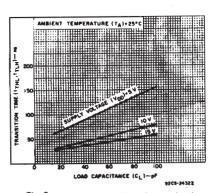


Fig. 9 - Typical transition time vs. load capacitance.

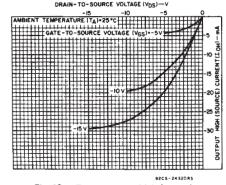


Fig. 10 — Typical output high (source) current characteristics.

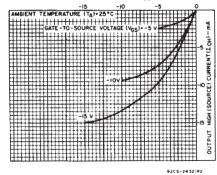


Fig. 11 — Minimum output high (source) current characteristics.

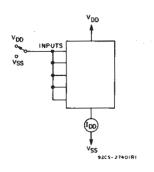


Fig. 12 - Quiescent device current test circuit.

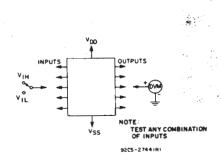


Fig. 13 - Input voltage test circuit.

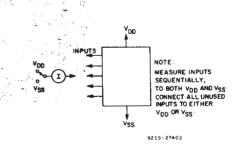


Fig. 14 - Input current test circuit.

CD4085B Types

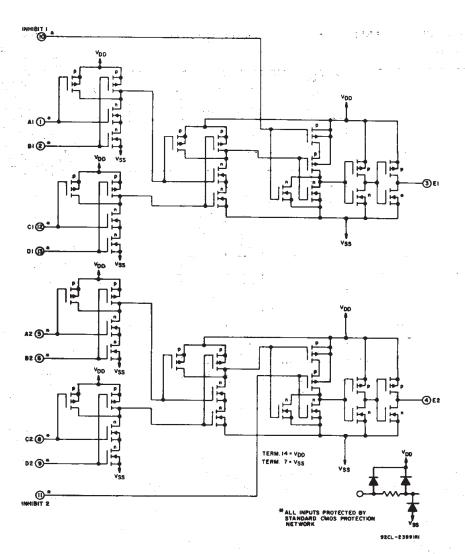
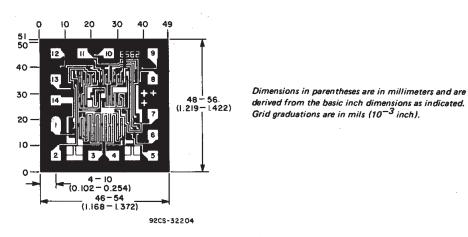


Fig. 15 - CD4085'schematic diagram.



Dimensions and Pad Layout for CD40858H.

www.ti.com 1-May-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
part number	(1)	(2)			(3)	(4)	(5)		(6)
CD4085BE	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4085BE
CD4085BF	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4085BF
CD4085BF3A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4085BF3A
CD4085BM	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4085BM
CD4085BPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM085B

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

www.ti.com 1-May-2025

OTHER QUALIFIED VERSIONS OF CD4085B, CD4085B-MIL:

Military : CD4085B-MIL

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	` '	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ı	CD4085BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



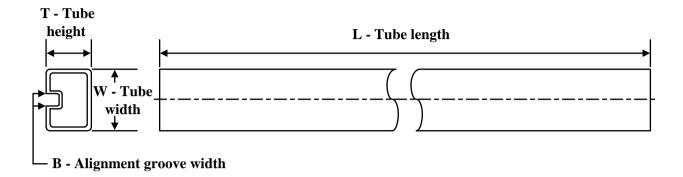
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4085BPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4085BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4085BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4085BM	D	SOIC	14	50	506.6	8	3940	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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